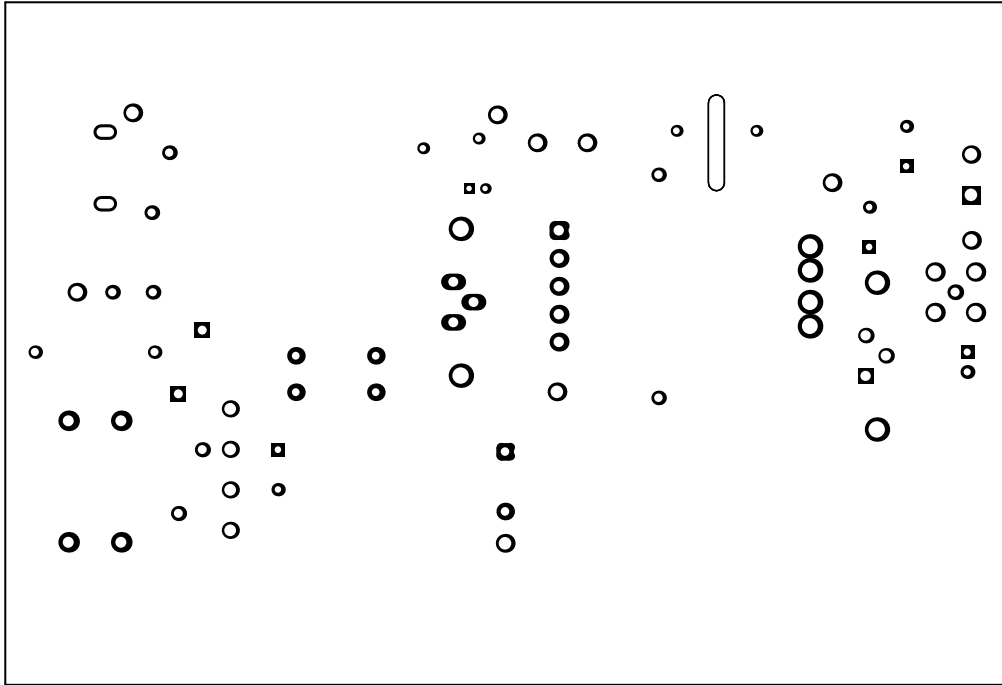
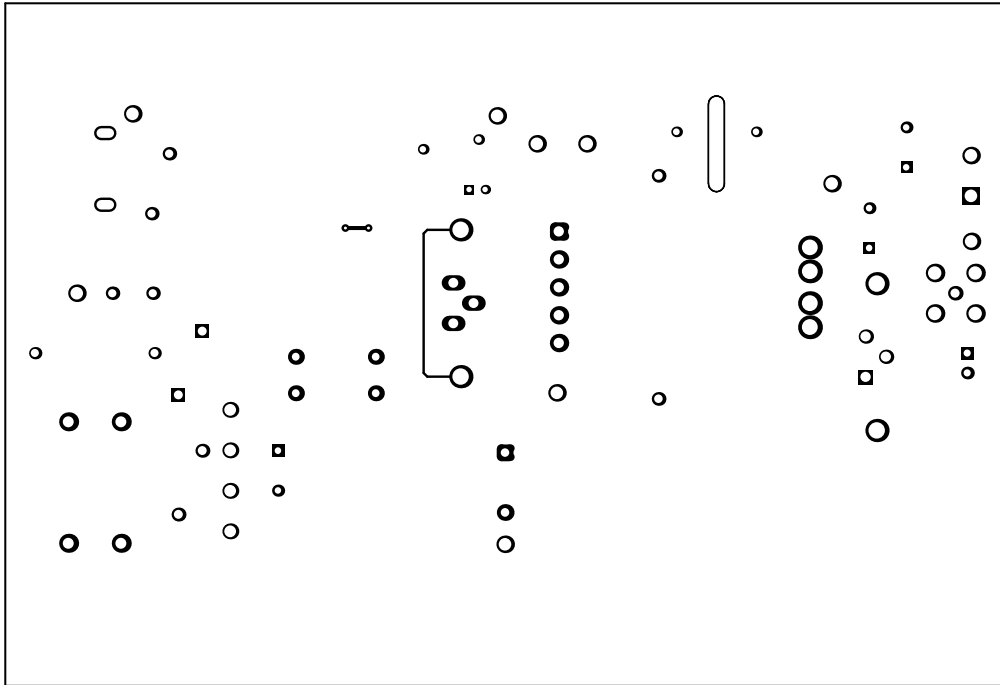


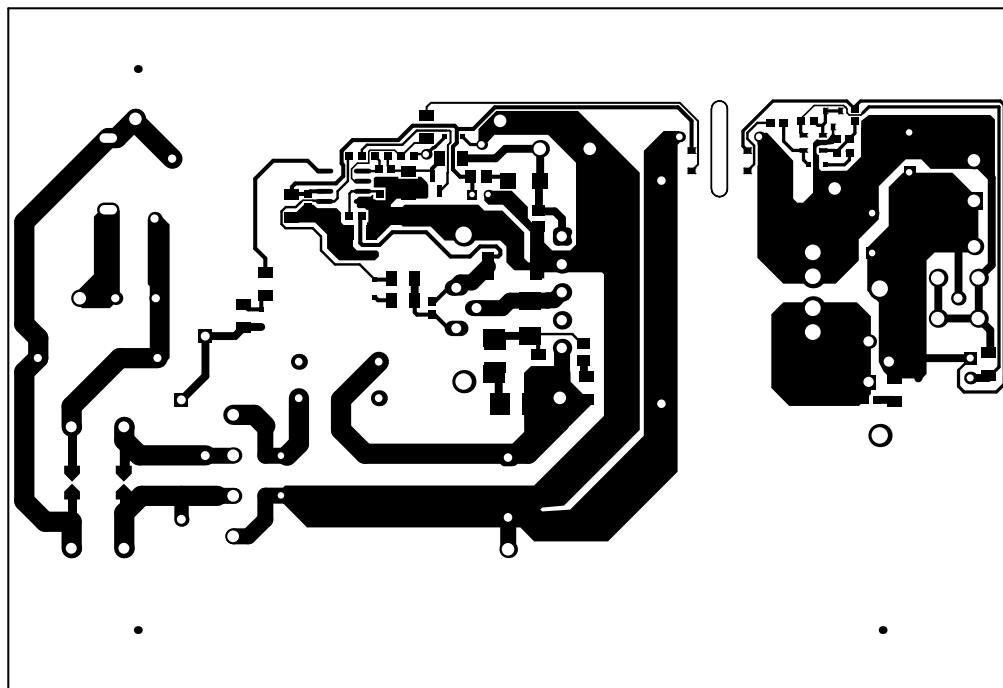
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9208	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 15/04/2014 12:40:01	TEXAS INSTRUMENTS	



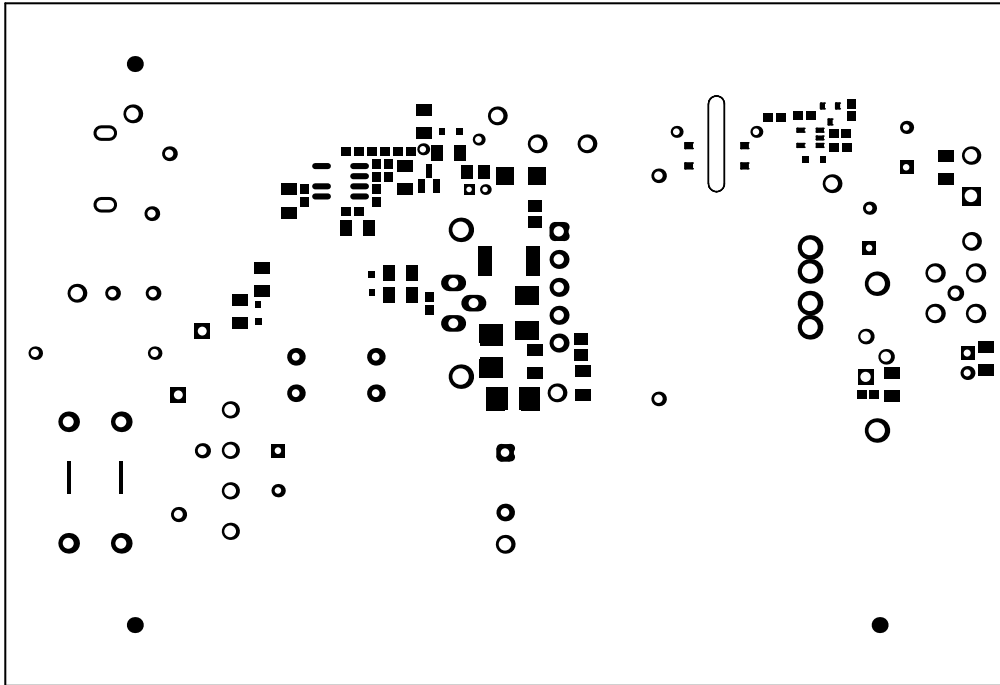
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9208	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 15/04/2014 12:40:02	TEXAS INSTRUMENTS	



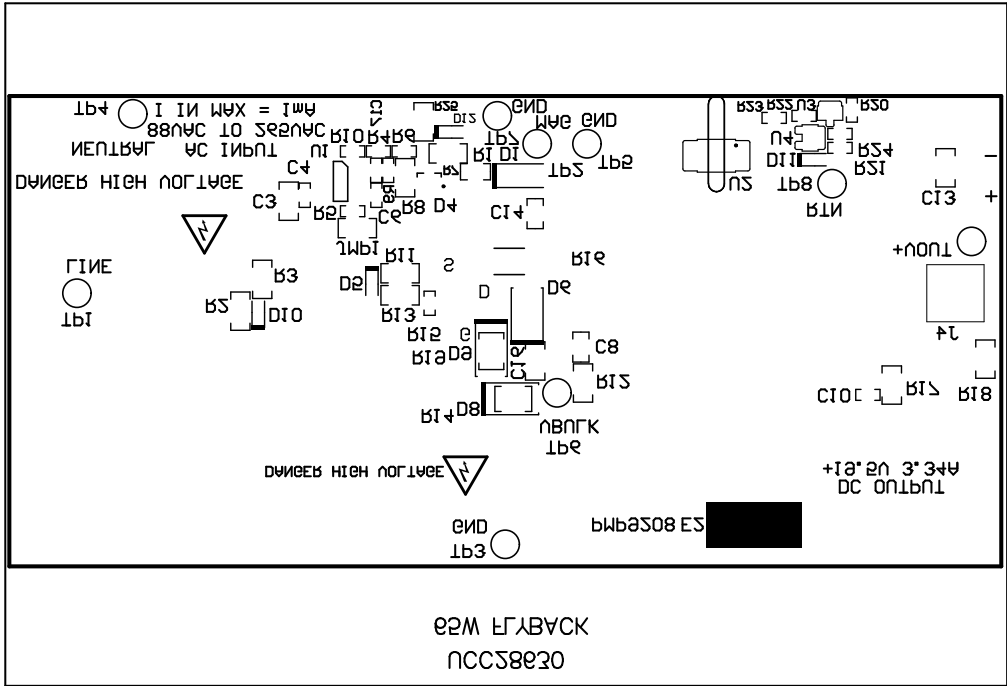
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9208	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 15/04/2014 12:40:02	TEXAS INSTRUMENTS	



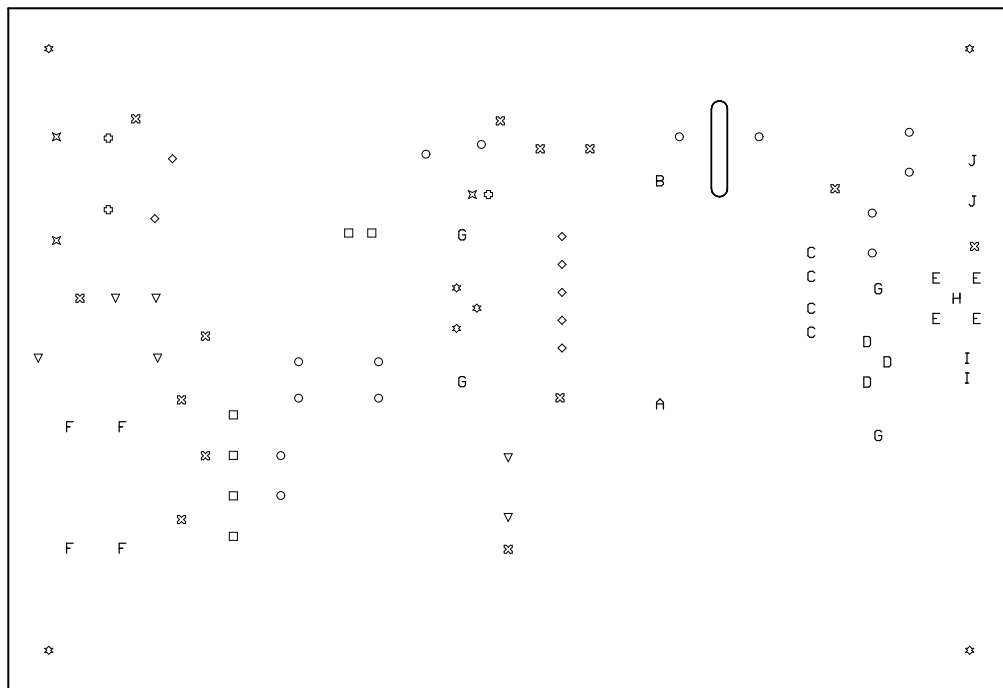
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9208	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 15/04/2014 12:40:03	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9208	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 15/04/2014 12:40:03	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9208	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 15/04/2014 12:40:04	TEXAS INSTRUMENTS	

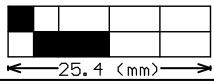
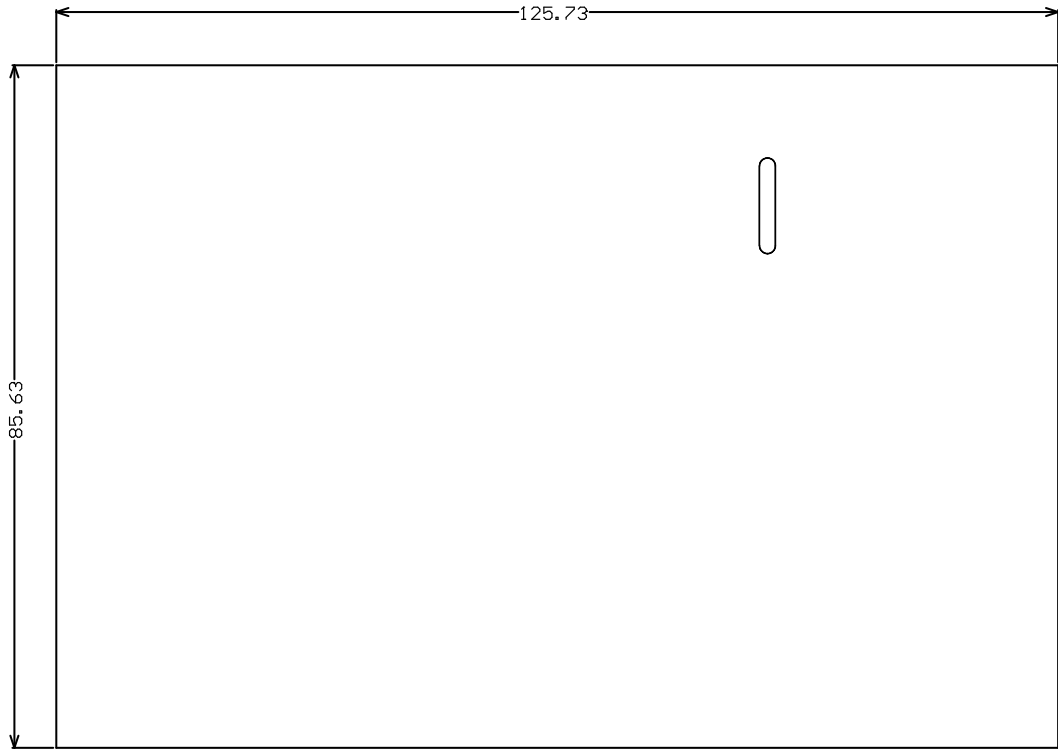


Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	H
□	2	0.4mm (15.748mil)			PTH	R
⊗	1	0.711mm (28mil)			PTH	R
⊕	1	0.712mm (28.012mil)			PTH	R
○	10	0.85mm (33.465mil)			PTH	R
I	2	0.914mm (35.984mil)			PTH	R
○	4	1mm (39.37mil)			PTH	R
▽	4	1.05mm (41.339mil)			PTH	R
◇	2	1.067mm (42mil)			PTH	R
A	1	1.092mm (42.992mil)			PTH	R
B	1	1.092mm (43mil)			PTH	R
▽	2	1.1mm (43.307mil)			PTH	R
⊗	4	1.15mm (45.276mil)			PTH	R
H	1	1.168mm (46mil)			PTH	R
⊗	3	1.27mm (50mil)			PTH	R
D	3	1.3mm (51.181mil)			PTH	R
◇	5	1.321mm (52mil)			PTH	R
F	4	1.4mm (55.118mil)			PTH	R
□	4	1.5mm (59.055mil)			PTH	R
J	2	1.6mm (62.992mil)			PTH	R
⊗	9	1.6mm (63mil)			PTH	R
E	4	1.702mm (67mil)			PTH	R
C	4	2mm (78.74mil)			PTH	R
G	4	2.083mm (82mil)			PTH	R
⊗	2	3mm (118.11mil)			NPTH	R
⊗	4	3.6mm (141.732mil)			NPTH	R
⊕	2	1.2mm (47.244mil)	2.2mm (86.614mil)	1mm (39.37mil)	PTH	S
85 Total						

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end
 Physical Length = Rout Path Length + Tool Size = Slot length as defined

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9208	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 15/04/2014 12:40:04	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9208	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 15/04/2014 12:40:07	TEXAS INSTRUMENTS	

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